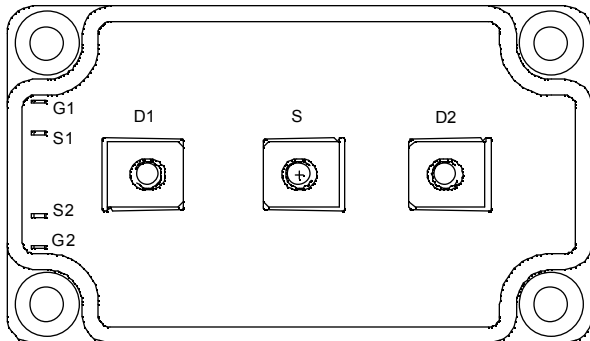
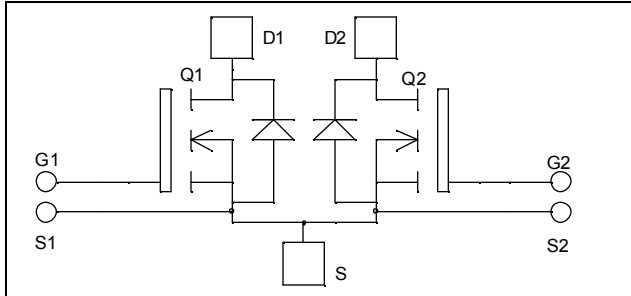


## Dual common source MOSFET Power Module

$V_{DSS} = 200V$   
 $R_{DSon} = 5m\Omega$  typ @  $T_j = 25^\circ C$   
 $I_D = 317A$  @  $T_c = 25^\circ C$



### Application

- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

### Features


- Power MOS 7<sup>®</sup> MOSFETs
  - Low  $R_{DSon}$
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

### Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_{DSS}$	Drain - Source Breakdown Voltage	200	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	317
		$T_c = 80^\circ C$	237
$I_{DM}$	Pulsed Drain current	1268	
$V_{GS}$	Gate - Source Voltage	$\pm 30$	V
$R_{DSon}$	Drain - Source ON Resistance	6	$m\Omega$
$P_D$	Maximum Power Dissipation	$T_c = 25^\circ C$	1136
$I_{AR}$	Avalanche current (repetitive and non repetitive)	89	A
$E_{AR}$	Repetitive Avalanche Energy	50	mJ
$E_{AS}$	Single Pulse Avalanche Energy	2500	


**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 200V$			400	$\mu\text{A}$
		$V_{GS} = 0V, V_{DS} = 160V$			2000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 158.5A$		5	6	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{mA}$	3		5	V
$I_{GSS}$	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 200$	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{MHz}$		27.4		nF
$C_{oss}$	Output Capacitance			8.72		
$C_{rss}$	Reverse Transfer Capacitance			0.38		
$Q_g$	Total gate Charge	$V_{GS} = 10V$ $V_{Bus} = 100V$ $I_D = 300A$		448		nC
$Q_{gs}$	Gate – Source Charge			172		
$Q_{gd}$	Gate – Drain Charge			188		
$T_{d(on)}$	Turn-on Delay Time	<b>Inductive switching @ <math>125^\circ\text{C}</math></b> $V_{GS} = 15V$ $V_{Bus} = 133V$ $I_D = 300A$ $R_G = 1.2\Omega$		28		ns
$T_r$	Rise Time			56		
$T_{d(off)}$	Turn-off Delay Time			81		
$T_f$	Fall Time			99		
$E_{on}$	Turn-on Switching Energy	<b>Inductive switching @ <math>25^\circ\text{C}</math></b> $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 300A, R_G = 1.2\Omega$		1852		$\mu\text{J}$
$E_{off}$	Turn-off Switching Energy			1820		
$E_{on}$	Turn-on Switching Energy	<b>Inductive switching @ <math>125^\circ\text{C}</math></b> $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 300A, R_G = 1.2\Omega$		2432		$\mu\text{J}$
$E_{off}$	Turn-off Switching Energy			2124		

**Source - Drain diode ratings and characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_S$	Continuous Source current (Body diode)		$T_c = 25^\circ\text{C}$		317	A
			$T_c = 80^\circ\text{C}$		237	
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V, I_S = -300A$			1.3	V
$dv/dt$	Peak Diode Recovery ①				5	V/ns
$t_{rr}$	Reverse Recovery Time	$I_S = -300A, V_R = 100V$ $di_S/dt = 400A/\mu\text{s}$		284		ns
$Q_{rr}$	Reverse Recovery Charge			12.24		$\mu\text{C}$

 ①  $dv/dt$  numbers reflect the limitations of the circuit rather than the device itself.

$$I_S \leq -300A \quad di/dt \leq 700A/\mu\text{s} \quad V_R \leq V_{DSS} \quad T_j \leq 150^\circ\text{C}$$

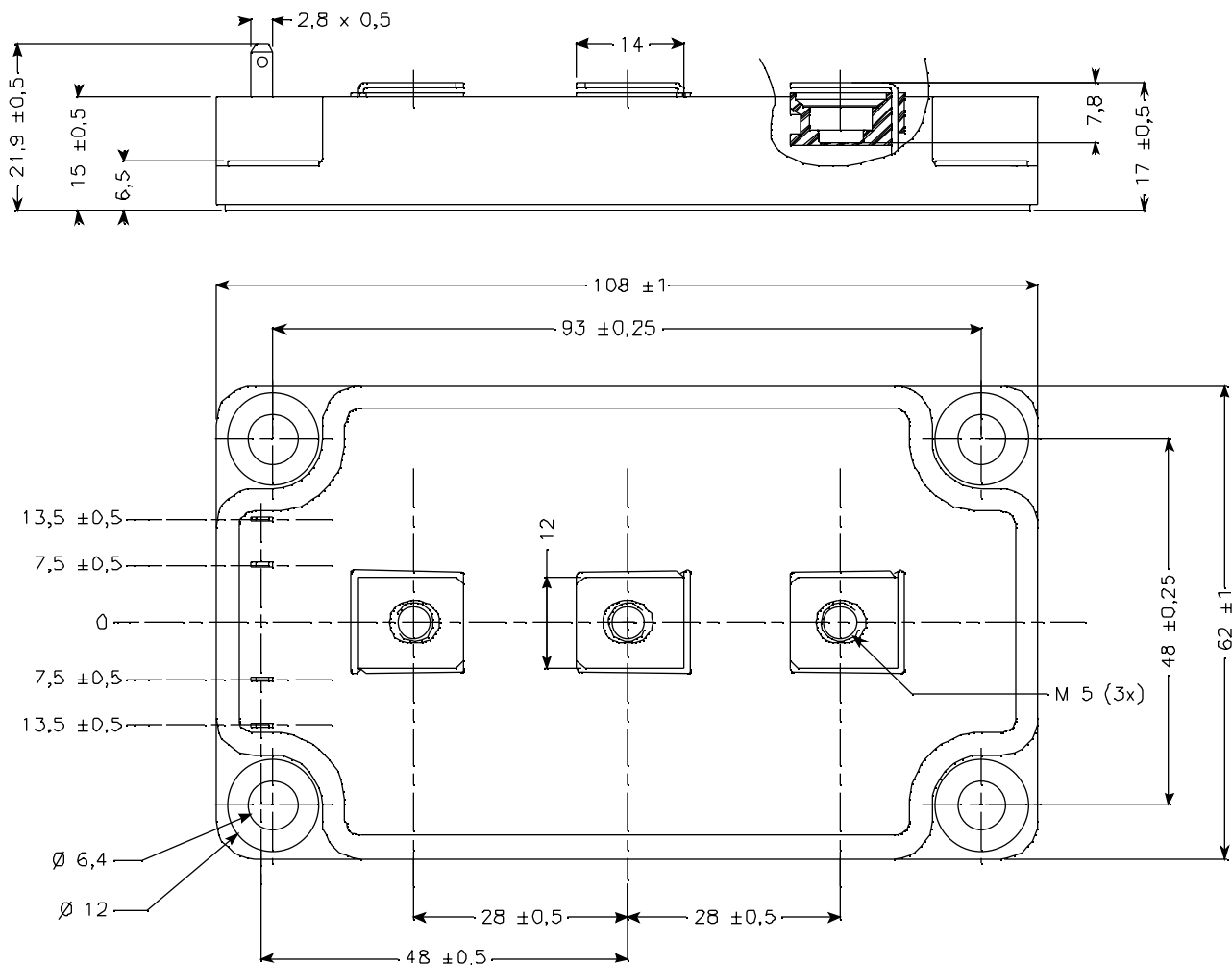
### Thermal and package characteristics

*Symbol Characteristic*

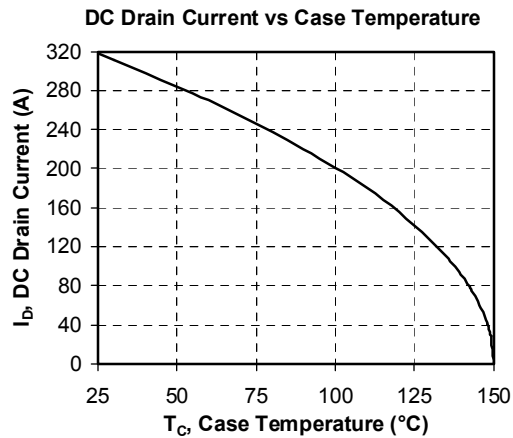
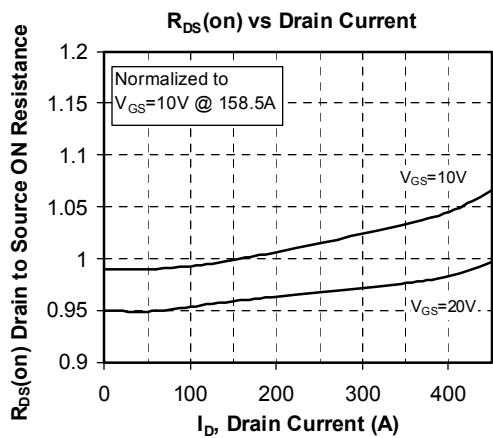
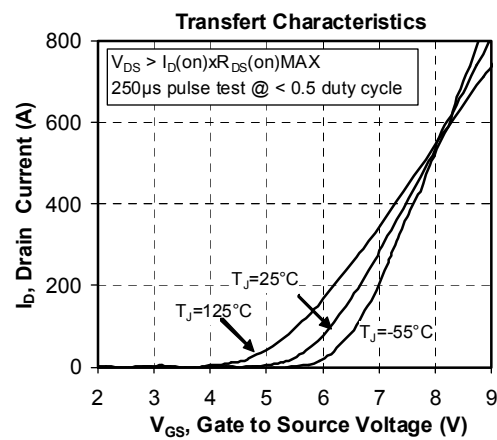
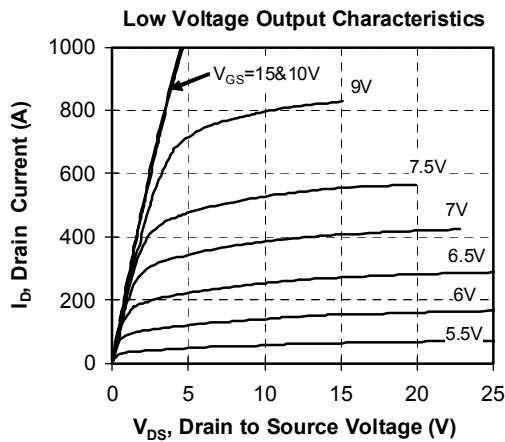
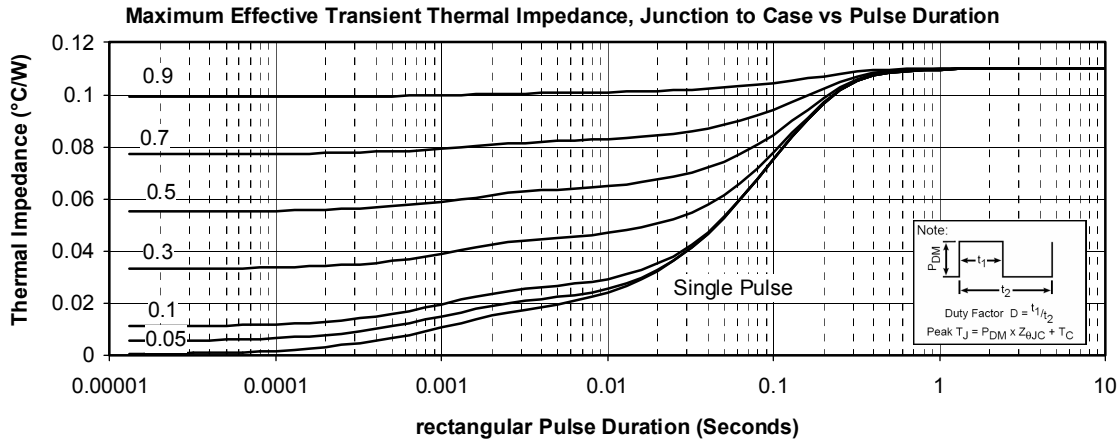
*Min Typ Max Unit*

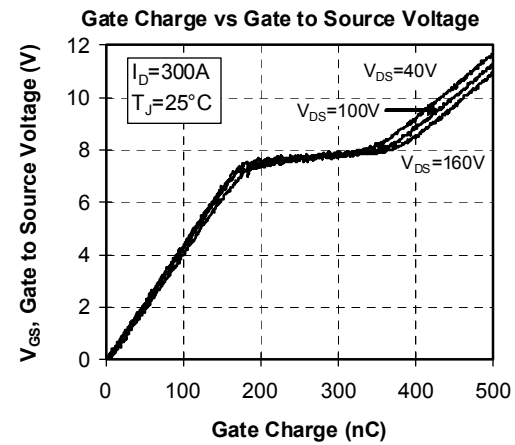
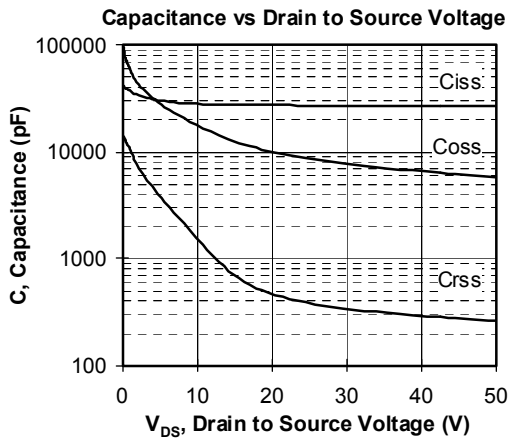
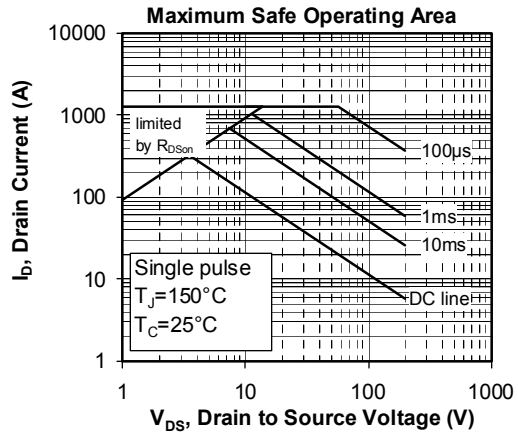
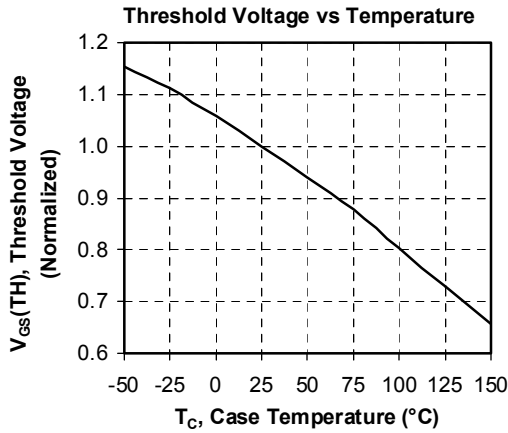
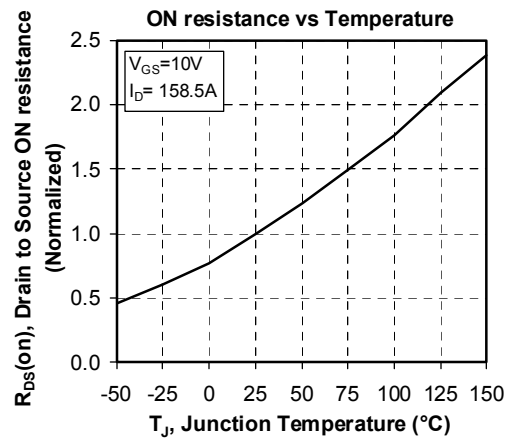
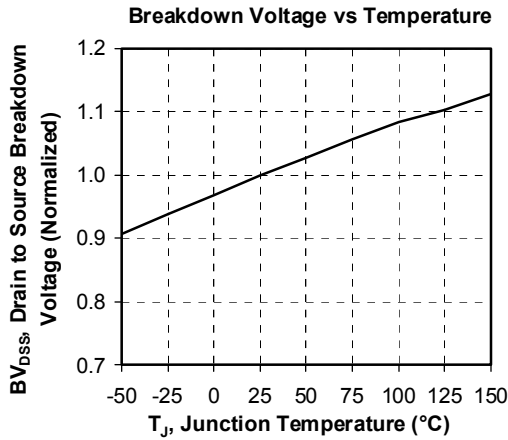
<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>	
$R_{thJC}$	Junction to Case Thermal Resistance			0.11	°C/W	
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case $t=1\text{ min}$ , $I_{isol}<1\text{mA}$ , 50/60Hz	2500			V	
$T_J$	Operating junction temperature range	-40		150	°C	
$T_{STG}$	Storage Temperature Range	-40		125		
$T_C$	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package Weight			280	g	

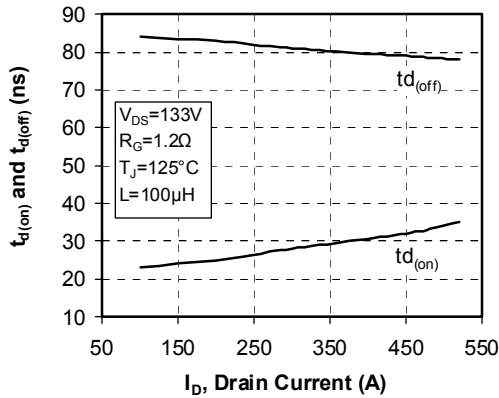
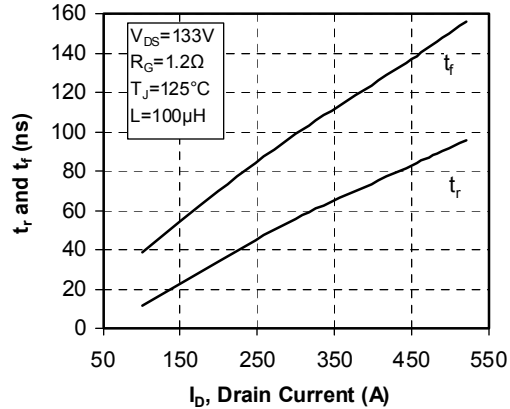
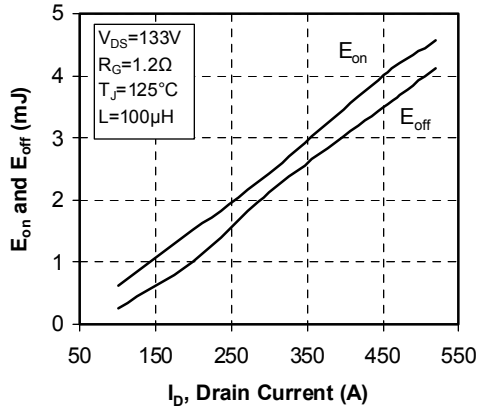
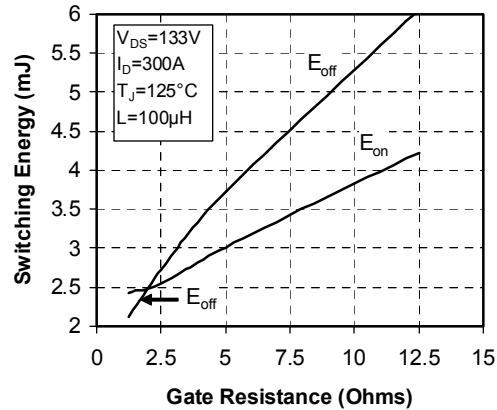
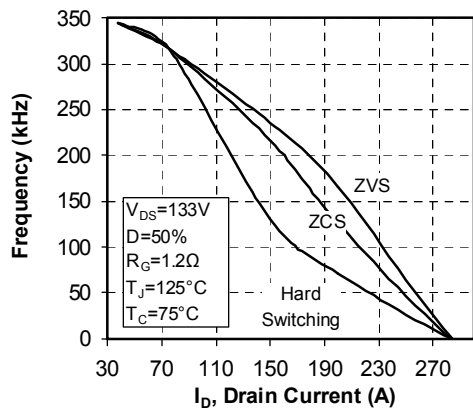
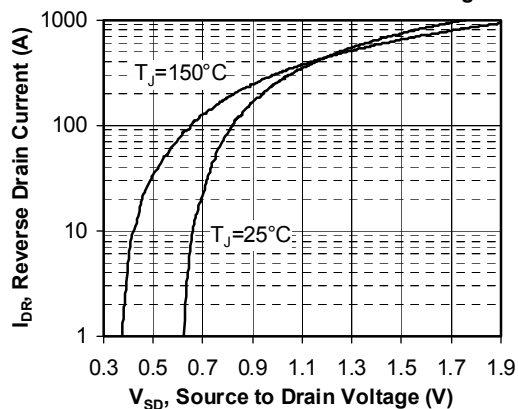
### SP6 Package outline (dimensions in mm)



See application note APT0601 - Mounting Instructions for SP6 Power Modules on [www.microsemi.com](http://www.microsemi.com)

**Typical Performance Curve**




**Delay Times vs Current**

**Rise and Fall times vs Current**

**Switching Energy vs Current**

**Switching Energy vs Gate Resistance**

**Operating Frequency vs Drain Current**

**Source to Drain Diode Forward Voltage**


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